

Zynq UltraScale+ RFSoc Product Tables and Product Selection Guide



		Device Name	ZU21DR	ZU25DR	ZU27DR	ZU28DR	ZU29DR
Processing System (PS)	Application Processor Unit	Processor Core	Quad-core ARM® Cortex™-A53 MPCore™ up to 1.5GHz				
		Memory w/ECC	L1 Cache 32KB I / D per core, L2 Cache 1MB, on-chip Memory 256KB				
	Real-Time Processor Unit	Processor Core	Dual-core ARM Cortex-R5 MPCore up to 533MHz				
		Memory w/ECC	L1 Cache 32KB I / D per core, Tightly Coupled Memory 128KB per core				
	External Memory	Dynamic Memory Interface	x32/x64: DDR4, LPDDR4, DDR3, DDR3L, LPDDR3 with ECC				
		Static Memory Interfaces	NAND, 2x Quad-SPI				
	Connectivity	High-Speed Connectivity	PCIe® Gen2 x4, 2x USB3.0, SATA 3.1, DisplayPort, 4x Tri-mode Gigabit Ethernet				
		General Connectivity	2xUSB 2.0, 2x SD/SDIO, 2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO				
	Integrated Block Functionality	Power Management	Full / Low / PL / Battery Power Domains				
		Security	RSA, AES, and SHA				
AMS - System Monitor		10-bit, 1MS/s – Temperature and Voltage Monitor					
PS to PL Interface		12 x 32/64/128b AXI Ports					
Programmable Logic (PL)	RF Data Converter Subsystem	12-bit, 4GSPS RF-ADC w/DDC	0	8	8	8	0
		12-bit, 2GSPS RF-ADC w/DDC	0	0	0	0	16
		14-bit, 6.4GSPS RF-DAC w/DUC	0	8	8	8	16
		SD-FEC	8	0	0	8	0
	Programmable Functionality	System Logic Cells (K)	930	678	930	930	930
		CLB LUTs (K)	425	310	425	425	425
		Max. Distributed RAM (Mb)	13.0	9.6	13.0	13.0	13.0
	Memory	Total Block RAM (Mb)	38.0	27.8	38.0	38.0	38.0
		UltraRAM (Mb)	22.5	13.5	22.5	22.5	22.5
		DSP Slices	4,272	3,145	4,272	4,272	4,272
	Integrated IP	PCI Express® Gen 3x16 / Gen4x8	2	1	2	2	2
		150G Interlaken	1	1	1	1	1
		100G Ethernet MAC/PCS w/RS-FEC	2	1	2	2	2
		AMS - System Monitor	1	1	1	1	1
	Speed Grades		-1E, -1I, -1LI, -2E, -2LE, -2I	-1E, -1I, -1LI, -2E, -2LE, -2I, -3E	-1E, -1I, -1LI, -2E, -2LE, -2I, -3E	-1E, -1I, -1LI, -2E, -2LE, -2I	-1E, -1I, -1LI, -2E, -2LE, -2I, -3E
	Package Footprint	Package Dimensions	PSIO, HDIO, HPIO GTR, GTY, RF-ADC, RF-DAC	PSIO, HDIO, HPIO GTR, GTY, RF-ADC, RF-DAC	PSIO, HDIO, HPIO GTR, GTY, RF-ADC, RF-DAC	PSIO, HDIO, HPIO GTR, GTY, RF-ADC, RF-DAC	PSIO, HDIO, HPIO GTR, GTY, RF-ADC, RF-DAC
	D1156	35x35	214, 72, 208 4, 16, 0, 0				
E1156	35x35		214, 48, 104 4, 8, 8, 8	214, 48, 104 4, 8, 8, 8	214, 48, 104 4, 8, 8, 8		
G1517	40x40		214, 48, 299 4, 8, 8, 8	214, 48, 299 4, 16, 8, 8	214, 48, 299 4, 16, 8, 8		
F1760	42.5x42.5					214, 96, 312 4, 16, 16, 16	

Zynq® UltraScale+™ RFSoc Ordering Information



E = Extended (Tj = 0°C to +100°C)
I = Industrial (Tj = -40°C to +100°C)

Note: -L2E (Tj = 0°C to +110°C)

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